

BFG590; BFG590/X

NPN 5 GHz wideband transistors

Rev. 04 — 12 November 2007 Product data sheet

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NPN 5 GHz wideband transistors BFG590; BFG590/X

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

APPLICATIONS

- MATV/CATV amplifiers and RF communications subscriber equipment in the GHz range
- Ideally suitable for use in class-A, (A)B and C amplifiers with either pulsed or continuous drive.

DESCRIPTION

NPN silicon planar epitaxial transistor in a 4-pin dual-emitter SOT143B plastic package.

MARKING

TYPE NUMBER	CODE
BFG590	%MH
BFG590/X	%MN

PINNING

PIN	DESCRIPTION	
	BFG590	BFG590/X
1	collector	collector
2	base	emitter
3	emitter	base
4	emitter	emitter

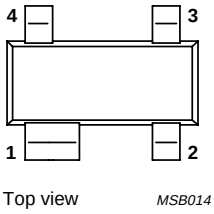


Fig.1 Simplified outline SOT143B.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	–	15	V
I_C	collector current (DC)		–	–	200	mA
P_{tot}	total power dissipation	$T_s \leq 60$ °C	–	–	400	mW
h_{FE}	DC current gain	I_C = 35 mA; V_{CE} = 8 V	50	90	280	
C_{re}	feedback capacitance	I_C = 0; V_{CE} = 8 V; f = 1 MHz	–	0.7	–	pF
f_T	transition frequency	I_C = 80 mA; V_{CE} = 4 V; f = 1 GHz	–	5	–	GHz
G_{UM}	maximum unilateral power gain	I_C = 80 mA; V_{CE} = 4 V; f = 900 MHz; T_{amb} = 25 °C	–	13	–	dB
$\|S_{21}\|^2$	insertion power gain	I_C = 80 mA; V_{CE} = 4 V; f = 900 MHz; T_{amb} = 25 °C	–	11	–	dB

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	3	V
I_C	collector current (DC)		–	200	mA
P_{tot}	total power dissipation	$T_s \leq 60$ °C; see Fig.2; note 1	–	400	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	$T_s \leq 60$ °C; note 1	290	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.

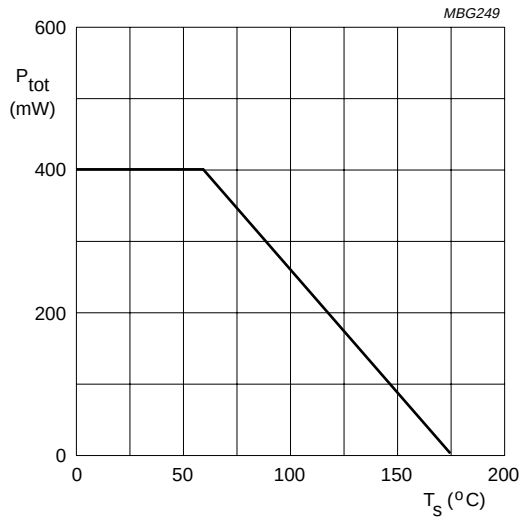


Fig.2 Power derating curve.

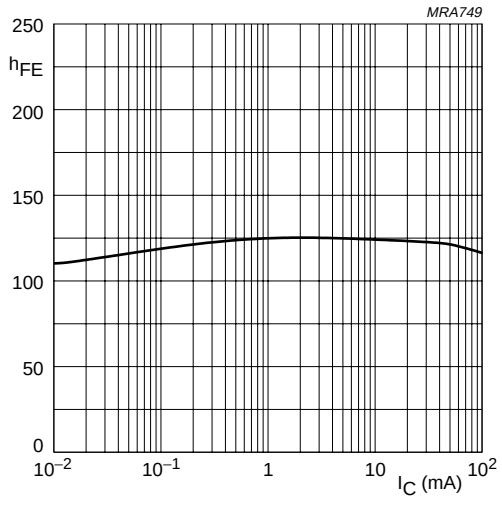
CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	I_C = 0.1 mA; I_E = 0	20	–	–	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	I_C = 10 mA; I_B = 0	15	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	I_E = 0.1 mA; I_C = 0	3	–	–	V
I_{CBO}	collector-base leakage current	V_{CB} = 10 V; I_E = 0	–	–	100	nA
h_{FE}	DC current gain	I_C = 70 mA; V_{CE} = 8 V; see Fig.3	60	120	250	
f_T	transition frequency	I_C = 80 mA; V_{CE} = 4 V; f = 1 GHz; see Fig.5	–	5	–	GHz
C_{re}	feedback capacitance	I_C = 0; V_{CB} = 8 V; f = 1 MHz; see Fig.4	–	0.7	–	pF
G_{UM}	maximum unilateral power gain; note 1	I_C = 80 mA; V_{CE} = 4 V; f = 900 MHz; T_{amb} = 25 °C	–	13	–	dB
		I_C = 80 mA; V_{CE} = 4 V; f = 2 GHz; T_{amb} = 25 °C	–	7.5	–	dB
$\|S_{21}\|^2$	insertion power gain	I_C = 80 mA; V_{CE} = 4 V; f = 900 MHz; T_{amb} = 25 °C	–	11	–	dB

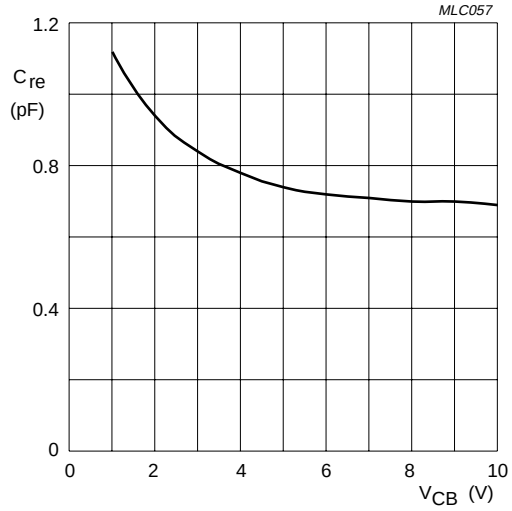
Note

1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)}$ dB.



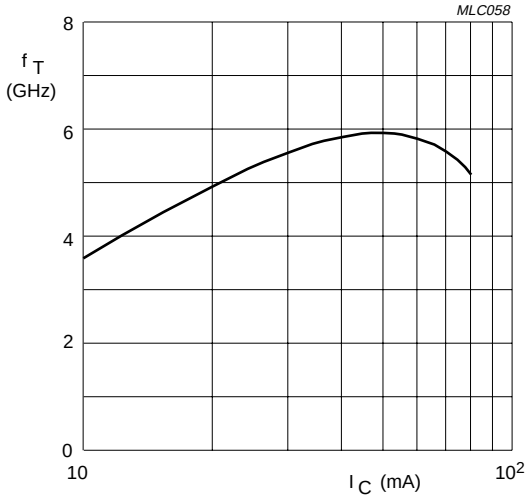
V_{CE} = 8 V.

Fig.3 DC current gain as a function of collector current; typical values.



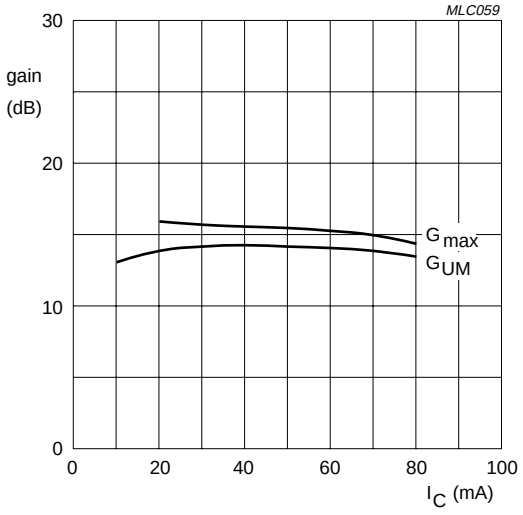
I_C = 0; f = 1 MHz.

Fig.4 Feedback capacitance as a function of collector-base voltage; typical values.



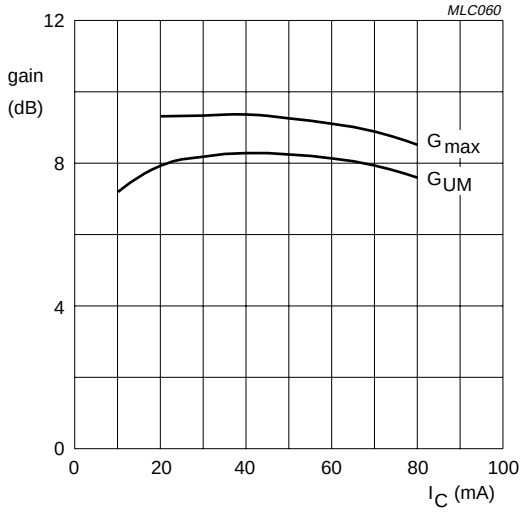
V_{CE} = 4 V; f = 1 GHz.

Fig.5 Transition frequency as a function of collector current; typical values.



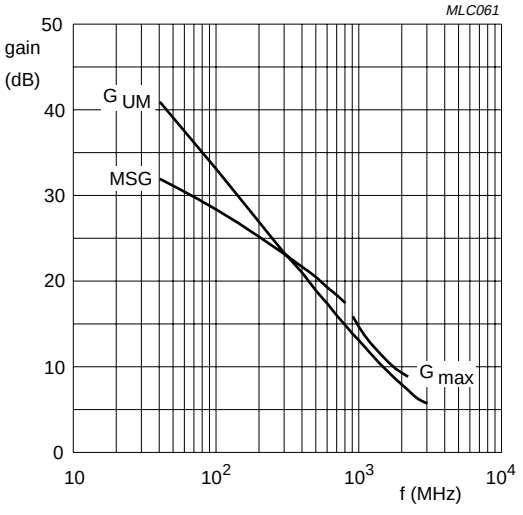
f = 900 MHz; V_{CE} = 4 V.

Fig.6 Gain as a function of collector current; typical values.



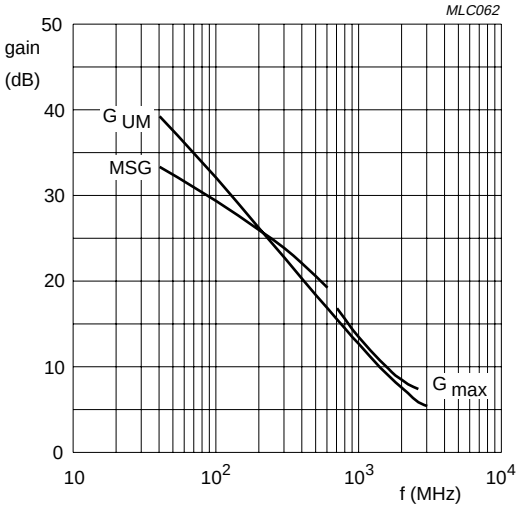
f = 2 GHz; V_{CE} = 4 V.

Fig.7 Gain as a function of collector current; typical values.



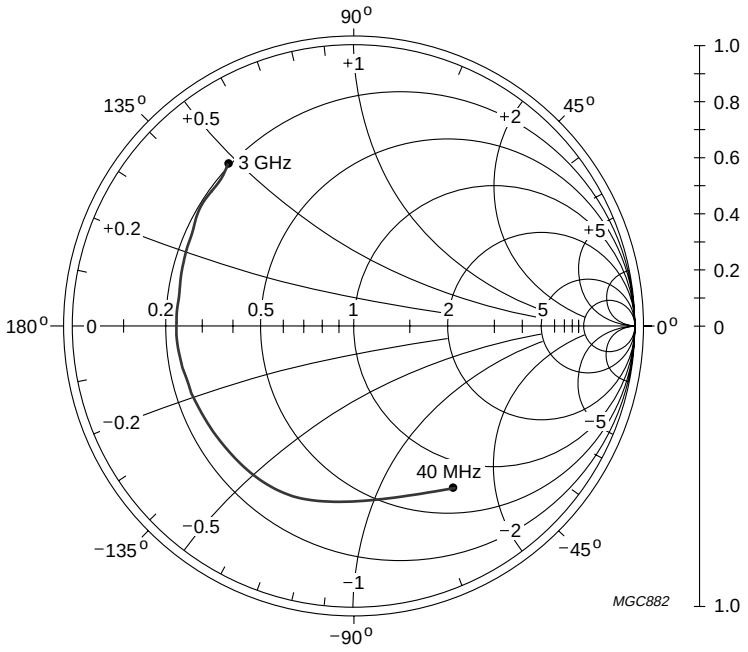
I_C = 20 mA; V_{CE} = 4 V.

Fig.8 Gain as a function of frequency; typical values.



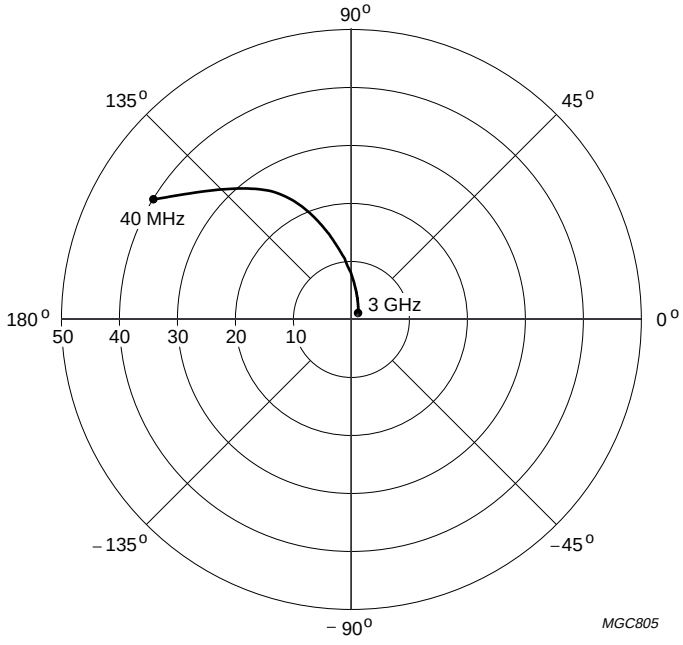
I_C = 80 mA; V_{CE} = 4 V.

Fig.9 Gain as a function of frequency; typical values.



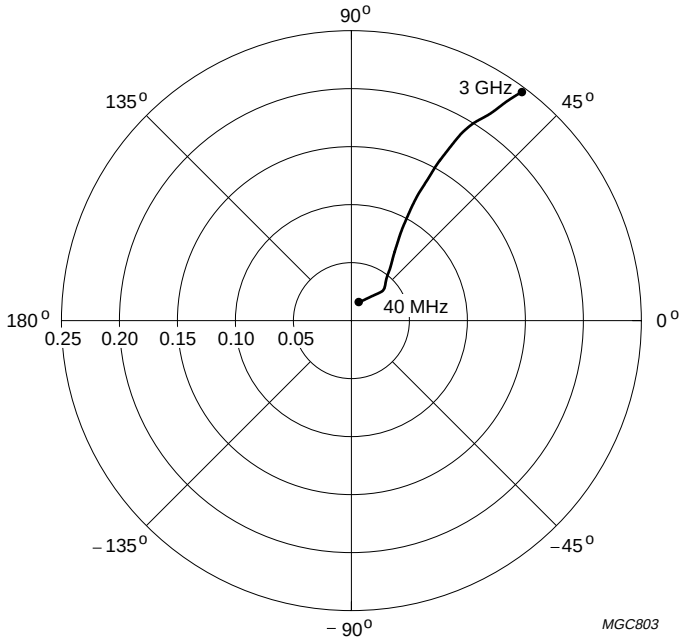
I_C = 80 mA; V_{CE} = 4 V; Z_o = 50 Ω.

Fig.10 Common emitter input reflection coefficient (S_{11}); typical values.



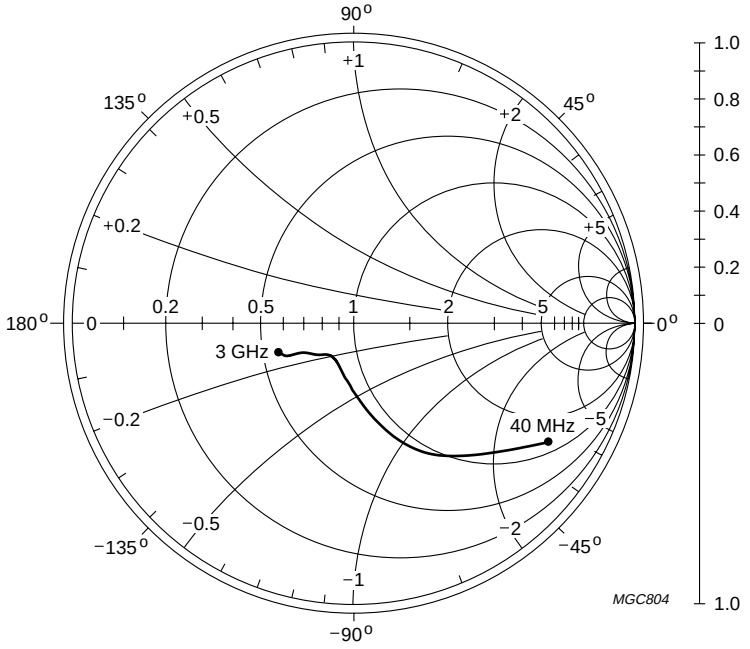
I_C = 80 mA; V_{CE} = 4 V.

Fig.11 Common emitter forward transmission coefficient (S_{21}); typical values.



I_C = 80 mA; V_{CE} = 4 V.

Fig.12 Common emitter reverse transmission coefficient (S_{12}); typical values.

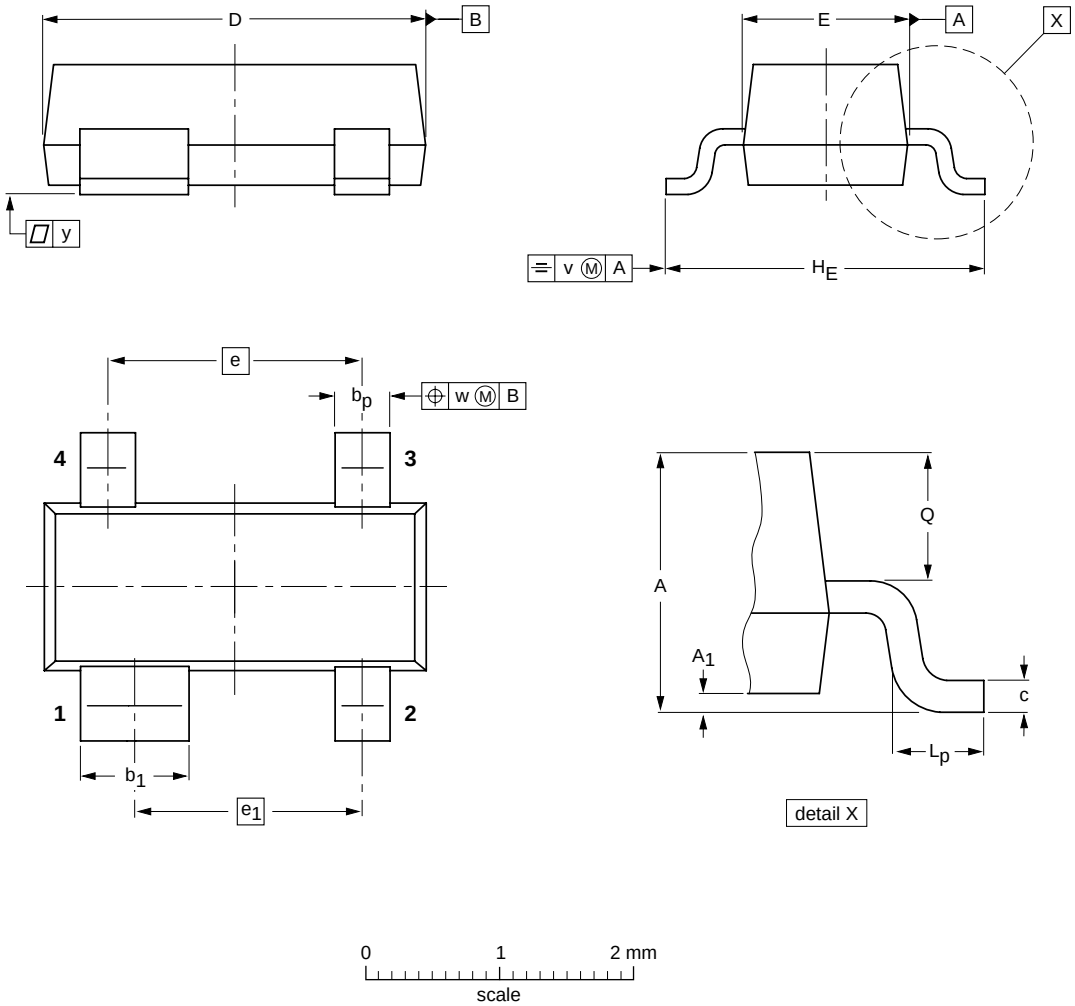


I_C = 80 mA; V_{CE} = 4 V; Z_o = 50 Ω.

Fig.13 Common emitter output reflection coefficient (S_{22}); typical values.

PACKAGE OUTLINE

Plastic surface mounted package; 4 leads **SOT143B**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT143B						97-02-28

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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[2] The term 'short data sheet' is explained in section "Definitions".

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